

## **IEEE ESTC 2024 – The place to be!**

Be a part of IEEE ESTC 2024 – the premier international event in the field of microelectronics and system integration, including their application in industry. The conference is organized every two years in Europe and is sponsored by IEEE-EPS in association with IMAPS Europe. This year it takes place in Berlin, Germany, from September 11-13, 2024. As we are finalizing the program, we would like to give you an overview of the program highlights.

### **Conference program now online!**

This year's IEEE ESTC Conference will feature roughly 120 oral and 70 poster presentations highlighting new developments in advanced packaging, wafer-level packaging, reliability of electronic devices and power electronics, to name but a few topics. As in previous years, the conference papers will be published in the conference proceedings and in the IEEE Xplore database.

The conference program is available on our website at <https://www.estc-conference.net/>.

Other highlights in the conference program include four [professional development courses](#) on the morning of the first conference day, an EPS HIR Workshop, Special Sessions on ChipsAct and IPCEI project, Photonics and Quantum Computing, Education and Green ICT as well as a Panel Discussion on "Chiplet Architectures for Automotive".

### **Keynote presentations**

We are delighted to welcome four distinguished packaging experts who will be presenting new findings from their respective areas of expertise:

- **Johanna M. Swan** (Intel Fellow and Director of Package Research and Systems Solutions in Components Research, Technology Development, Intel Corporation, USA)  
T.b.d.
- **Dr. Michael Hosemann** (Head of Digital Electronics at Healthineers Computed Tomography Detector Center, Siemens, Germany)  
**"Electronics Integration: Challenges in Computed Tomography Scanners"**
- **Dr. Yasumitsu Oriti** (Senior Managing Executive Officer in 3D Assembly Division, Rapidus Corporation, Japan)  
**"Challenges and Opportunities of Semiconductor Packaging in the Chiplet Era"**
- **Subramanian S. Iyer** (Director National Advanced Packaging Manufacturing Program, National Institute of Standards and Technology, USA)  
**"Packaging: Then, Now and in the Future"**

For details please check our [website](#).

### **IEEE ESTC 2024 Sponsoring and Exhibition Opportunities**

IEEE ESTC 2024 provides very attractive sponsorship and exhibition opportunities. The conference is the perfect place for you to present your products and services and to give your company or institution

strong visibility and access to more than 300 engineers, managers, and decision makers from all areas of the microelectronics and system integration community.

These include material, equipment, software tools, design and simulation, processes and services for semiconductor assembly, interconnect, packaging, test, process control and analysis technologies as well as market research.

**Check [our website](#) for the booths and sponsorship packages still available – they are going fast!**

**The early bird for sponsoring and exhibition packages has been extended to May 31, 2024!**